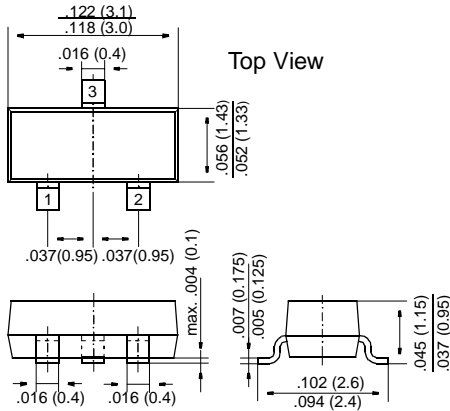


# BAV70

## Small Signal Diodes

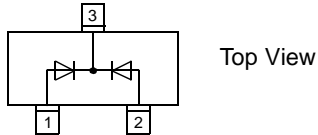
### SOT-23



Dimensions in inches and (millimeters)

### Marking

JJ



### FEATURES

- ◆ Silicon Epitaxial Planar Diodes
- ◆ Fast switching dual diode with common cathode
- ◆ This diode is also available in other configurations including: a dual anode to cathode with type designation BAV99, a dual common anode with type designation BAW56, and a single diode with type designation BAL99.



### MECHANICAL DATA

**Case:** SOT-23 Plastic Package

**Weight:** approx. 0.008 g

### MAXIMUM RATINGS AND ELECTRICAL CHARACTERISTICS

Ratings for a single diode at 25 °C ambient temperature unless otherwise specified.

	Symbol	Value	Unit
Reverse Voltage, Peak Reverse Voltage	$V_R, V_{RM}$	70	V
Forward Current (continuous)	$I_F$	250	mA
Non-Repetitive Peak Forward Current at $t = 1 \mu s$ at $t = 1 ms$ at $t = 1 s$	$I_{FSM}$ $I_{FSM}$ $I_{FSM}$	2 1 0.5	A A A
Power Dissipation at $T_{amb} = 25 \text{ }^\circ\text{C}$	$P_{tot}$	350 <sup>1)</sup>	mW
Junction Temperature	$T_j$	150	$^\circ\text{C}$
Storage Temperature Range	$T_S$	-65 to +150	$^\circ\text{C}$

<sup>1)</sup> Device on fiberglass substrate, see layout

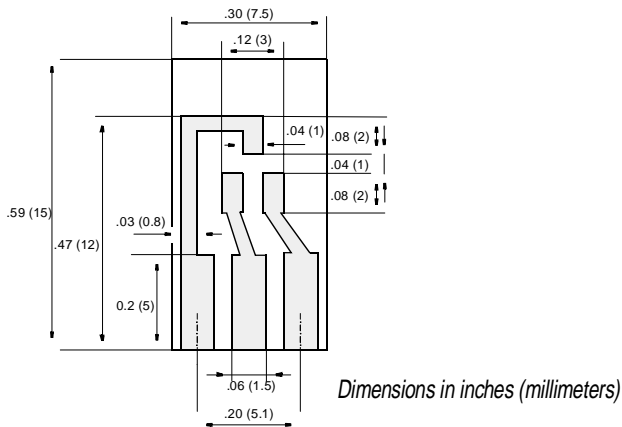
# BAV70

## ELECTRICAL CHARACTERISTICS

Ratings at 25 °C ambient temperature unless otherwise specified

	Symbol	Min.	Typ.	Max.	Unit
Forward Voltage at $I_F = 1 \text{ mA}$	$V_F$	–	–	0.715	V
at $I_F = 10 \text{ mA}$	$V_F$	–	–	0.855	V
at $I_F = 50 \text{ mA}$	$V_F$	–	–	1.0	V
at $I_F = 150 \text{ mA}$	$V_F$	–	–	1.25	V
Leakage Current at $V_R = 70 \text{ V}$	$I_R$	–	–	2.5	$\mu\text{A}$
at $V_R = 70 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	$I_R$	–	–	100	$\mu\text{A}$
at $V_R = 25 \text{ V}, T_j = 150 \text{ }^\circ\text{C}$	$I_R$	–	–	30	$\mu\text{A}$
Capacitance at $V_F = V_R = 0, f = 1 \text{ MHz}$	$C_{\text{tot}}$	–	–	1.5	pF
Reverse Recovery Time from $I_F = 10 \text{ mA}$ to $I_R = 10 \text{ mA}$ measured at $I_R = 1 \text{ mA}, R_L = 100 \text{ } \Omega$	$t_{\text{rr}}$	–	–	6	ns
Thermal Resistance Junction to Ambient Air	$R_{\text{thJA}}$	–	–	430 <sup>1)</sup>	K/W

<sup>1)</sup> Device on fiberglass substrate, see layout



### Layout for $R_{\text{thJA}}$ test

Thickness: Fiberglass 0.059 in (1.5 mm)

Copper leads 0.012 in (0.3 mm)